

MILITARY SPECIFICATION

MICROCIRCUITS, DIGITAL, BIPOLAR,
TTL, MAGNITUDE COMPARATORS,
MONOLITHIC SILICON

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the detail requirements for monolithic silicon Advanced Low Power Schottky TTL, magnitude comparator microcircuits. Two product assurance classes and a choice of case outlines and lead finishes are provided and are reflected in the complete part number.

1.2 Part number. The part number shall be in accordance with MIL-M-38510, and as specified herein.

1.2.1 Device type. The device type shall be as follows:

<u>Device type</u>	<u>Circuit</u>
01	4-Bit Comparator
02	4-Bit Comparator

1.2.2 Device class. The device class shall be the product assurance level as defined in MIL-M-38510.

1.2.3 Case outline. The case outline shall be designated as follows:

<u>Outline letter</u>	<u>Case outline (see MIL-M-38510, appendix C)</u>
E	D-2 (16-pin, 1/4" x 7/8"), dual-in-line package
F	F-5 (16-pin, 1/4" x 3/8"), flat package

1.3 Absolute maximum ratings.

Supply voltage range - - - - -	-0.5 V dc to +7.0 V dc
Input voltage range - - - - -	-1.5 V dc at -12 mA to +5.5 V dc
Storage temperature range - - - - -	-65°C to +150°C
Maximum power dissipation (P_D) per device 1/:	
Device 01 and 02 - - - - -	485 mW
Lead temperature (soldering 10 seconds) - - - - -	+300°C
Thermal resistance, junction to case (θ_{JC}):	
Cases E and F - - - - -	See MIL-M-38510, appendix C
Junction temperature (T_J) 2/ - - - - -	+175°C

1/ Must withstand the added P_D due to short circuit test (e.g., I_{OS}).

2/ Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions per method 5004 of MIL-STD-883.

Beneficial comments (recommendations, additions, deletions) and any pertinent data which may be of use in improving this document should be addressed to: Rome Air Development Center (RBE-2), Griffiss AFB, NY 13441, by using the self-addressed Standardization Document Improvement Proposal (OD Form 1426) appearing at the end of this document or by letter.

1.4 Recommended operating conditions.

Supply voltage (V_{CC}) - - - - -	4.5 V dc minimum to 5.5 V dc maximum
Minimum high-level input voltage (V_{IH}) - - - - -	2.0 V dc
Maximum low-level input voltage (V_{IL}) - - - - -	0.8 V dc
Normalized fanout (each output) - - - - -	10 maximum
Case operating temperature range (T_C) - - - - -	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1. Government documents.

2.1.1 Specification and standard. The following specification and standard form a part of this specification to the extent specified herein. Unless otherwise specified, the issues of these documents shall be those listed in the issue of the Department of Defense Index of Specifications and Standards (DODISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARD

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of the specification and standard required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this specification and the references cited herein (except for associated detail specifications, specification sheets or MS standards), the text of this specification shall take precedence. Nothing in this specification, however, shall supersede applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Detail specification. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.2 Truth tables. The truth tables shall be as specified on figure 2.

3.2.3 Logic diagrams. The logic diagrams shall be as specified on figure 3.

3.2.4 Schematic circuits. The schematic circuits shall be submitted to the preparing activity prior to inclusion of a manufacturer's device in this specification and shall be submitted to the qualifying activity as a prerequisite for qualification. All manufacturers' schematics shall be maintained and available upon request.

3.2.5 Case outlines. The case outlines shall be as specified in 1.2.3.

3.3 Lead material and finish. The lead material and finish shall be in accordance with MIL-M-38510 and 6.4 herein.

3.4 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I, and apply over the full recommended case operating temperature range.

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Device type	Limits		Unit	
				Min	Max		
High-level output voltage	V_{OH}	$V_{CC} = 4.5 \text{ V}$, $V_{IH} = 2.0 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $I_{OH} = -400 \mu\text{A}$	01	2.4		V	
		$V_{CC} = 4.5 \text{ V}$, $V_{IH} = 2.0 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $I_{OH} = -800 \mu\text{A}$					
Low-level output voltage	V_{OL}	$V_{CC} = 4.5 \text{ V}$, $V_{IH} = 2.0 \text{ V}$, $V_{IL} = 0.8 \text{ V}$, $I_{OL} = 16 \text{ mA}$	A11	0.4		V	
Input clamp voltage	V_{IC}	$V_{CC} = 4.5 \text{ V}$, $I_{IN} = -12 \text{ mA}$, $T_C = 25^{\circ}\text{C}$	A11	-1.5		V	
High-level input current (All inputs except $A < B$ or $A > B$)	I_{IH1}	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 2.4 \text{ V}$	01	0	120	μA	
			02	0	80	μA	
High-level input current (all inputs)	I_{IH2}	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 5.5 \text{ V}$	01	0	300	μA	
			02	0	200	μA	
High-level input current ($A < B$, $A > B$ inputs)	I_{IH3}	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 2.4 \text{ V}$	01	0	40	μA	
Low-level input current (all other inputs)	I_{IL1}	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 0.4 \text{ V}$	01	-2.0	-4.3	mA	
			02	-1.4	-3.2	mA	
Low-level input current ($A < B$, $A > B$ inputs)	I_{IL2}	$V_{CC} = 5.5 \text{ V}$, $V_{IN} = 0.4 \text{ V}$	01	-0.7	-1.6	mA	
Short circuit output current	I_{OS}	$V_{CC} = 5.5 \text{ V}$ 1/	01	-20	-55	mA	
		$V_{CC} = 5.5 \text{ V}$ 1/	02	-20	-70	mA	
Supply current	I_{CC}	$V_{CC} = 5.5 \text{ V}$ 2/	01	88		mA	
		$V_{CC} = 5.5 \text{ V}$	02	81		mA	
Propagation delay from any A or B input to $A < B$ or $A > B$ outputs	t_{PLH1}	$C_L = 50 \text{ pF}$ 3 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	38	ns	
Propagation delay from any A or B input to $A > B$ output	t_{PLH2}	$C_L = 50 \text{ pF}$ 3 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	49	ns	

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Device type	Limits		Unit
				Min	Max	
Propagation delay from A < B or A = B input to A > B output	t _{PLH3}	$C_L = 50 \text{ pF}$ 2 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	19	ns
Propagation delay from A = B input to A = B output	t _{PLH4}	$C_L = 50 \text{ pF}$ 1 gate level 3/ 4/ $R_L = 400\Omega$	01	2	30	ns
Propagation delay from A > B or A = B input to A < B output	t _{PLH5}	$C_L = 50 \text{ pF}$ 2 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	19	ns
Propagation delay from any A or B input to A > B or A < B output	t _{PHL1}	$C_L = 50 \text{ pF}$ 3 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	43	ns
Propagation delay from any A or B input to A = B output	t _{PHL2}	$C_L = 50 \text{ pF}$ 3 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	43	ns
Propagation delay from A < B or A = B inputs to A > B output	t _{PHL3}	$C_L = 50 \text{ pF}$ 2 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	26	ns
Propagation delay from A = B input to A = B output	t _{PHL4}	$C_L = 50 \text{ pF}$ 1 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	26	ns
Propagation delay from A > B or A = B input to A < B output	t _{PHL5}	$C_L = 50 \text{ pF}$ 2 gate levels 3/ 4/ $R_L = 400\Omega$	01	2	26	ns
Propagation delay from E to A = B	t _{PLH1}	$V_{CC} = 5.0 \text{ V}$, $R_L = 390\Omega$, $C_L = 50 \text{ pF}$	02	3	22	ns
Propagation delay from E to A < B	t _{PLH2}	$V_{CC} = 5.0 \text{ V}$, $R_L = 390\Omega$, $C_L = 50 \text{ pF}$	02	3	25	ns
Propagation delay from E to A > B	t _{PLH3}	$V_{CC} = 5.0 \text{ V}$, $R_L = 390\Omega$, $C_L = 50 \text{ pF}$	02	3	25	ns
Propagation delay from A to A = B	t _{PLH4}	$V_{CC} = 5.0 \text{ V}$, $R_L = 390\Omega$, $C_L = 50 \text{ pF}$	02	9	55	ns
Propagation delay from B to A = B	t _{PLH5}	$V_{CC} = 5.0 \text{ V}$, $R_L = 390\Omega$, $C_L = 50 \text{ pF}$	02	9	55	ns

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq +125^{\circ}\text{C}$	Device type	Limits		Unit
				Min	Max	
Propagation delay from A to A < B	t _P LH6	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	6	39	ns
Propagation delay from B to A < B	t _P LH7	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	30	ns
Propagation delay from A to A > B	t _P LH8	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	30	ns
Propagation delay from B to A > B	t _P LH9	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	6	39	ns
Propagation delay from E to A = B	t _P HL1	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	19	ns
Propagation delay from E to A < B	t _P HL2	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	21	ns
Propagation delay from E to A > B	t _P HL3	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	21	ns
Propagation delay from A to A = B	t _P HL4	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	9	55	ns
Propagation delay from B to A = B	t _P HL5	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	9	55	ns
Propagation delay time from A to A < B	t _P HL6	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	6	32	ns
Propagation delay time from B to A < B	t _P HL7	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	26	ns
Propagation delay time from A to A > B	t _P HL8	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	3	25	ns
Propagation delay time from B to A > B	t _P HL9	V _{CC} = 5.0 V, R _L = 390Ω, C _L = 50 pF	02	6	35	ns

1/ Not more than one output should be shorted at a time.

2/ I_{CC} is measured with outputs open, A = B grounded, and all other inputs at 4.5 V.

3/ The longest gate level propagation delay paths are not tested (5 gate levels); however, they can be calculated: t = t_{p1} maximum + t_{p2} maximum - t_{p4} minimum.

4/ Gate level references are made with respect to the circuit logic diagram.

3.5 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (see table III)	
	Class S devices	Class B devices
Initial electrical parameters (pre burn-in) (method 5004)	1	1
Final electrical test parameters (method 5004)	1*,2,3,7, 9,10,11	1*,2,3, 7,9
Group A test requirements (method 5005)	1,2,3,7, 8,9,10,11	1,2,3,7, 9,10,11
Group B test requirements (method 5005) subgroup 5	1,2,3,7, 8,9,10,11	N/A
Group C end-point electrical parameters (method 5005)	N/A	1,2,3
Additional electrical subgroups for group C periodic inspections	N/A	None
Group D end-point electrical parameters (method 5005)	1,2,3	1,2,3

*PDA applies to subgroup 1 (see 4.2c).

3.6 Marking. Marking shall be in accordance with MIL-M-38510.

3.7 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 5 (see MIL-M-38510, appendix E).

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and methods 5005 and 5007, as applicable, of MIL-STD-883, except as modified herein.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. The following additional criteria shall apply:

a. Burn-in (method 1015 of MIL-STD-883).

(1) Test condition D or E, using the circuit shown on figure 4, or equivalent.

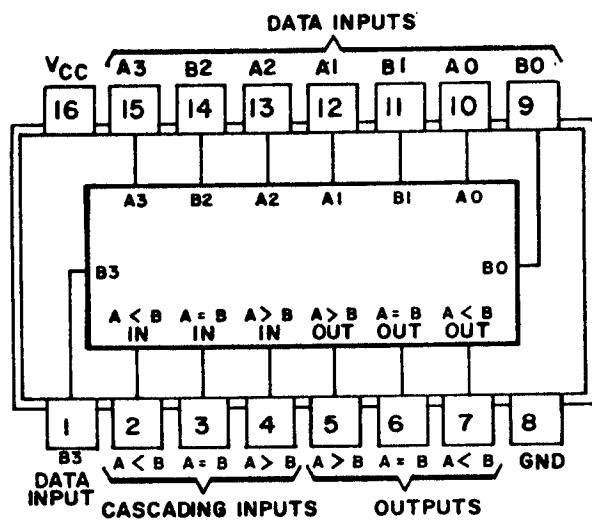
(2) $T_A = +125^\circ\text{C}$ minimum.

b. Initial and final electrical test parameters shall be as specified in table II, except initial electrical parameters tests prior to burn-in are optional at the discretion of the manufacturer.

c. The percent defective allowable (PDA) shall be as specified in MIL-M-38510.

Device type 01

Cases E and F



Device type 02

Cases E and F

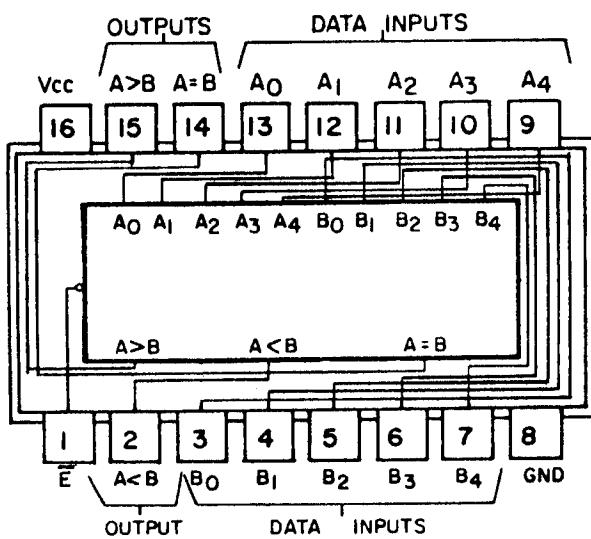


FIGURE 1. Terminal connections.

Device type 01

COMPARING INPUTS				CASCAADING INPUTS			OUTPUTS		
A3, B3	A2, B2	A1, B1	A0, B0	A > B	A < B	A = B	A > B	A < B	A = B
A3 > B3	X	X	X	X	X	X	H	L	L
A3 < B3	X	X	X	X	X	X	L	H	L
A3 = B3	A2 > B2	X	X	X	X	X	H	L	L
A3 = B3	A2 < B2	X	X	X	X	X	L	H	L
A3 = B2	A2 = B2	A1 > B1	X	X	X	X	H	L	L
A3 = B3	A2 = B2	A1 < B1	X	X	X	X	L	H	L
A3 = B3	A2 = B2	A1 = B1	A0 > B0	X	X	X	H	L	L
A3 = B3	A2 = B2	A1 = B1	A0 < B0	X	X	X	L	H	L
A3 = B3	A2 = B2	A1 = B1	A0 = B0	H	L	L	H	L	L
A3 = B3	A2 = B2	A1 = B1	A0 = B0	L	H	L	L	H	L
A3 = B3	A2 = B2	A1 = B1	A0 = B0	L	L	H	L	L	H
A3 = B3	A2 = B2	A1 = B1	A0 = B0	X	X	H	L	L	H
A3 = B3	A2 = B2	A1 = B1	A0 = B0	H	H	L	L	L	L
A3 = B3	A2 = B2	A1 = B1	A0 = B0	L	L	L	H	H	L

Device type 02

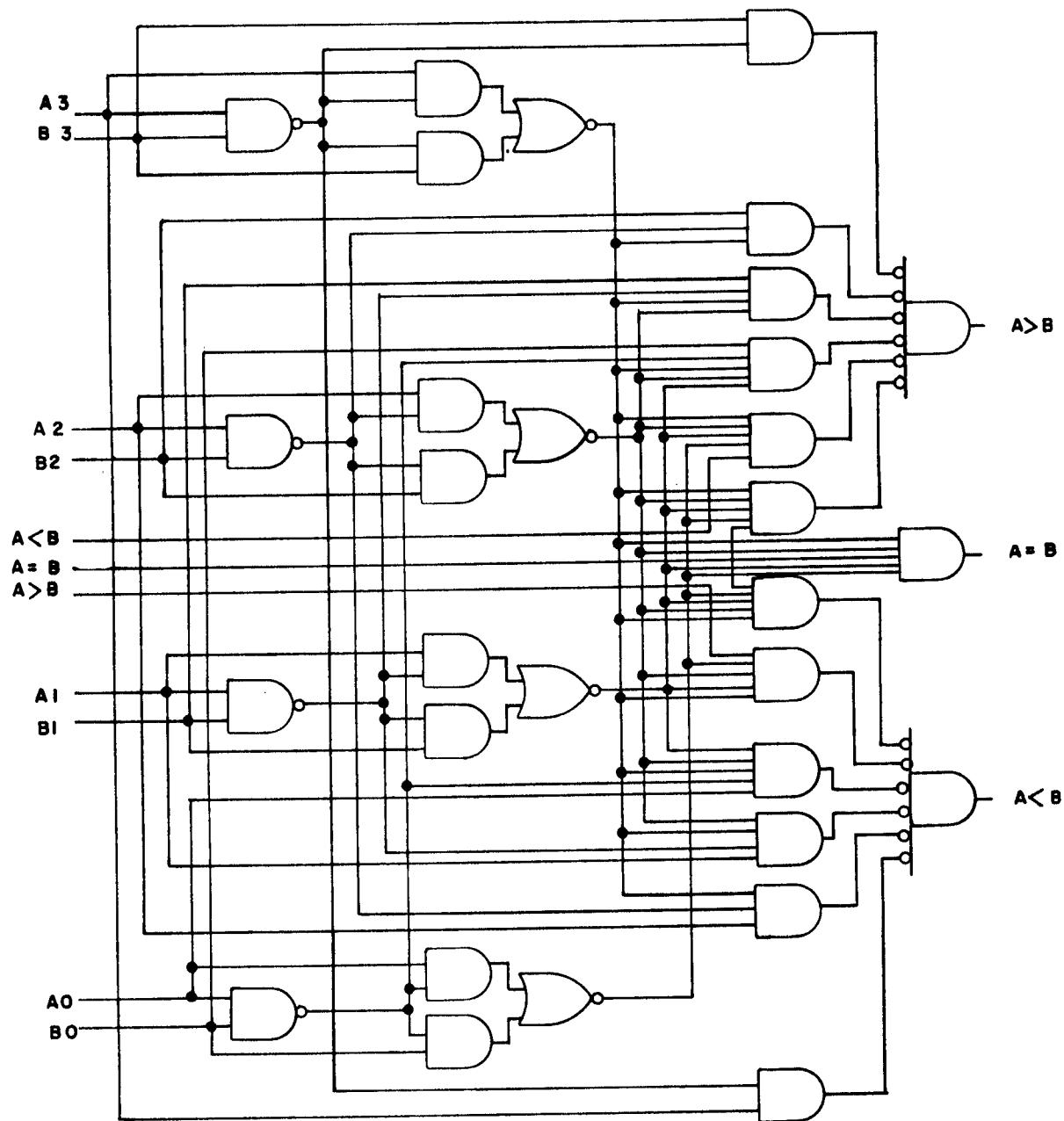
\bar{E}	Ay	By	A' < B	A > B	A = B
H	X	X	L	L	L
L	Word A = Word B		L	L	H
L	Word A > Word B		L	H	L
L	Word B > Word A		H	L	L

H = High level

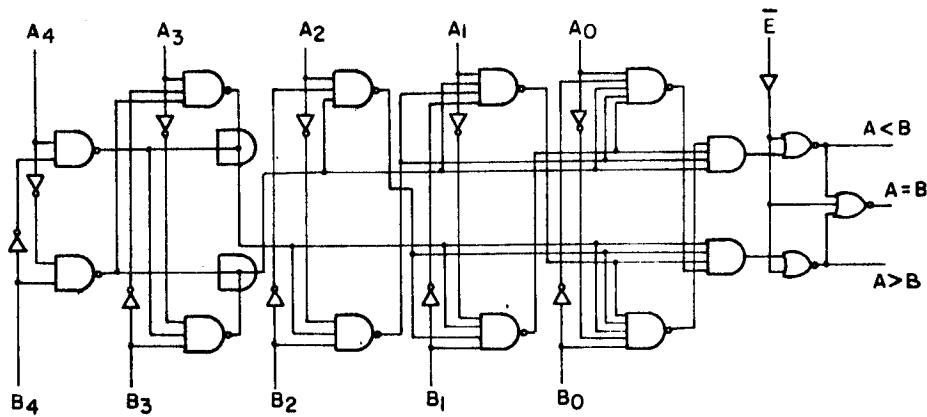
L = Low level

X = Irrelevant

FIGURE 2. Truth table.

Device type 01FIGURE 3. Logic diagram.

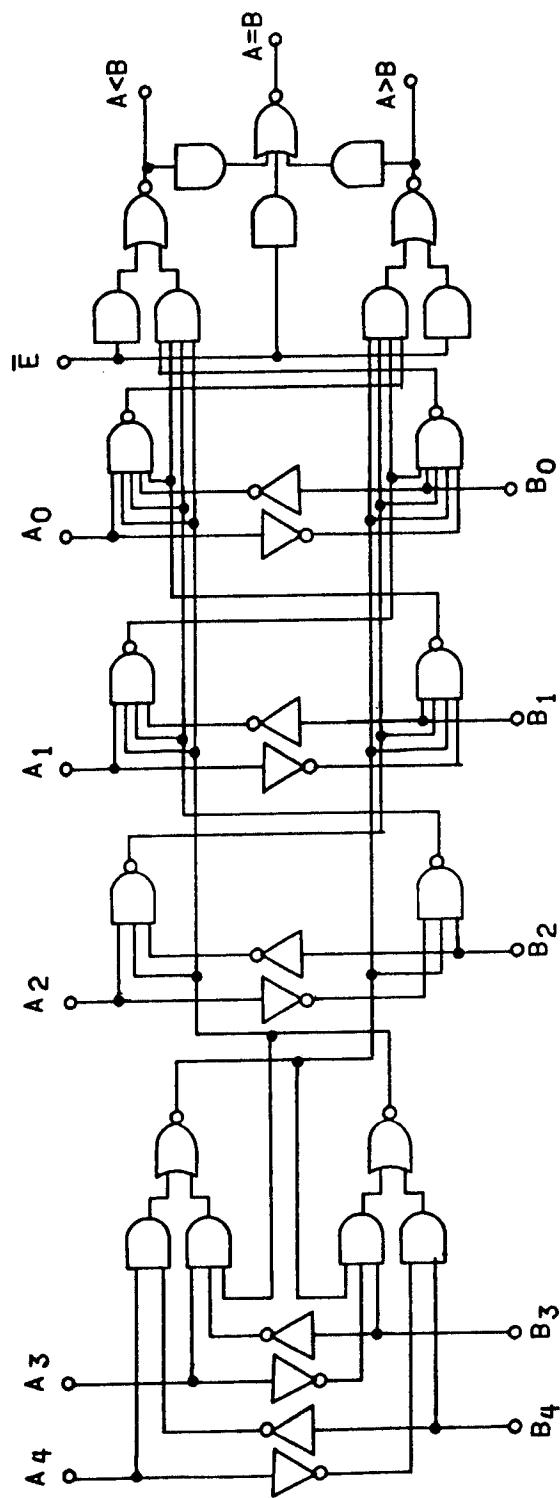
Device type 02



Circuit A

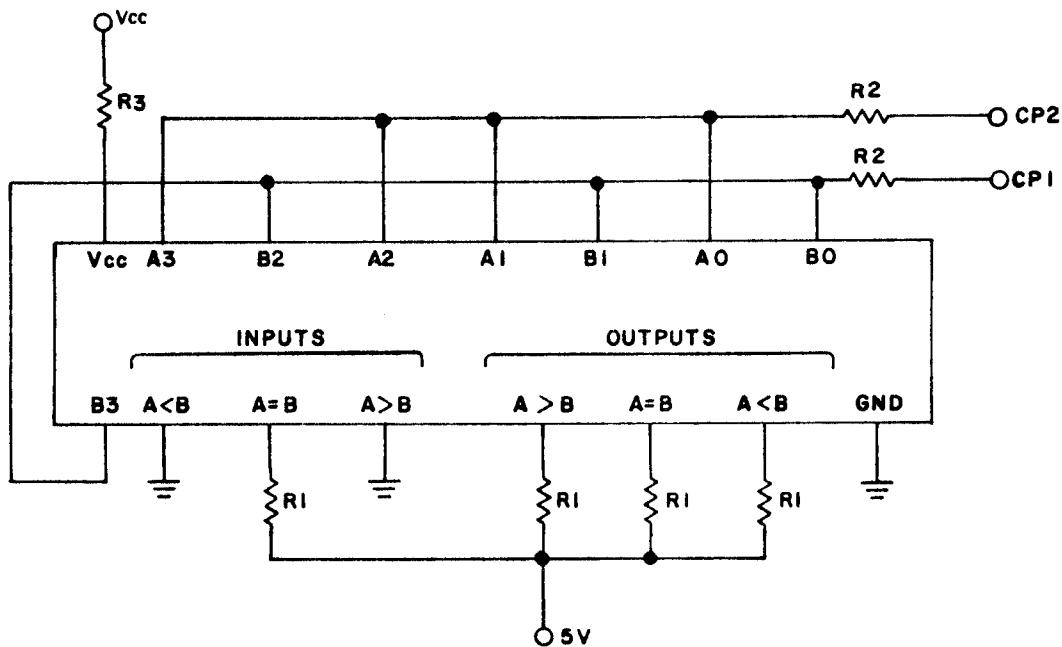
FIGURE 3. Logic diagram-- Continued.

Device type 02



Circuit B

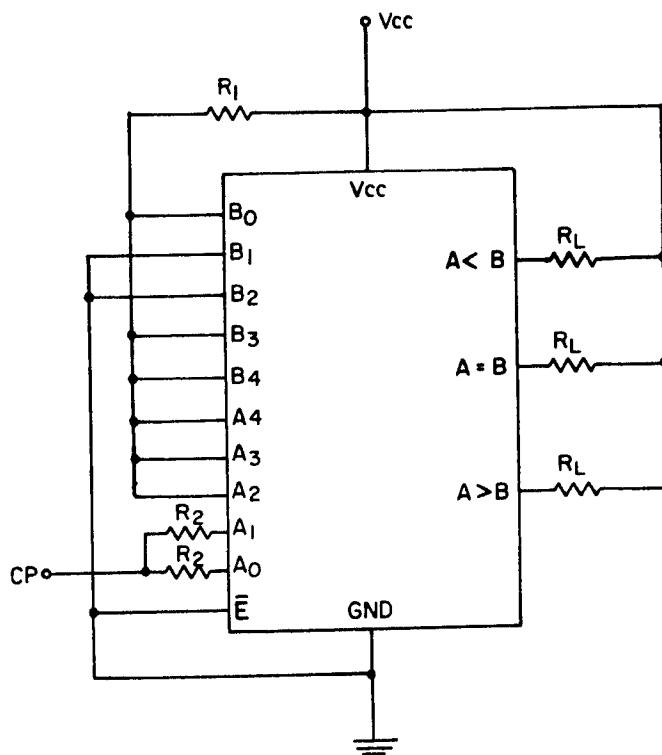
FIGURE 3. Logic diagram - Continued

Device type 01

NOTES:

1. CP1 = 100 kHz, 50% duty cycle, 0-3 V.
2. CP2 = 50 kHz, 50% duty cycle, 0-3 V.
3. R1 = $220\Omega \pm 5\%$.
4. R2 = $27\Omega \pm 5\%$.
5. R3 = $5.0\Omega \pm 5\%$.
6. V_{CC} shall be high enough to ensure 5.0 V minimum at the device terminal.

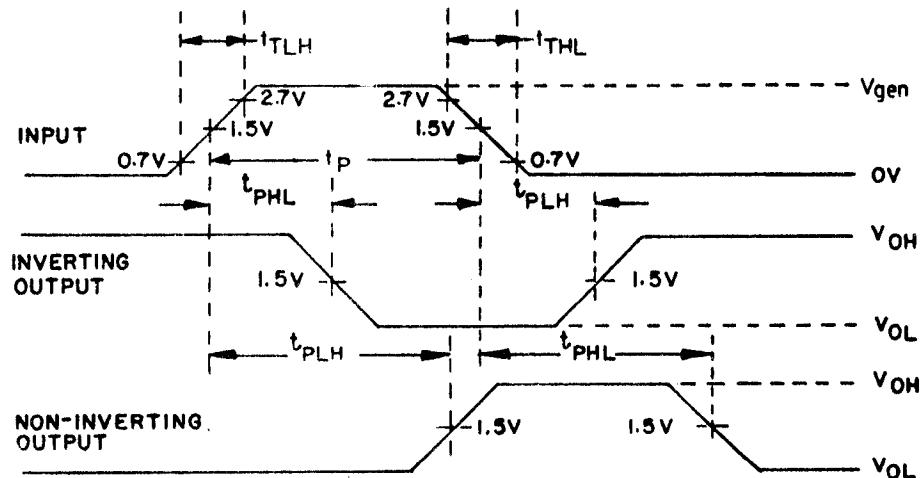
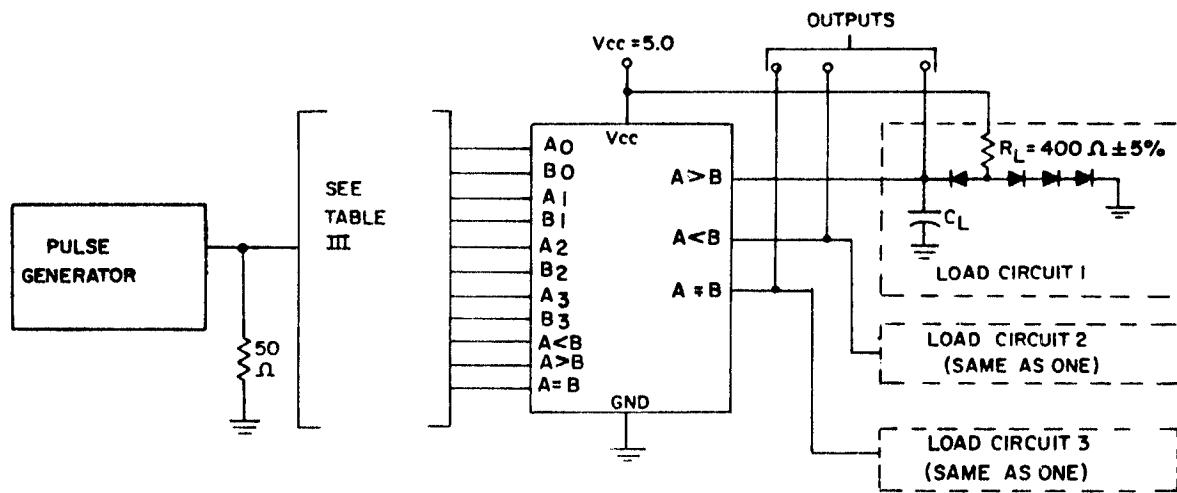
FIGURE 4. Burn-in and life test circuit.

Device type 02

NOTES

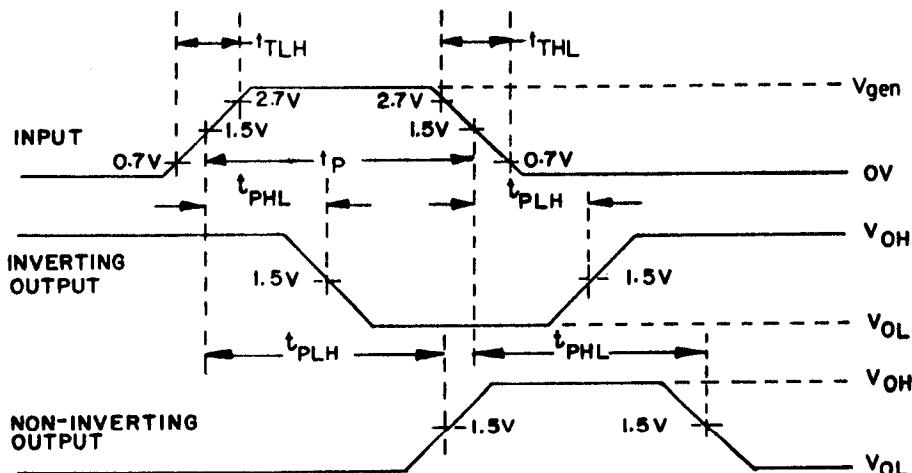
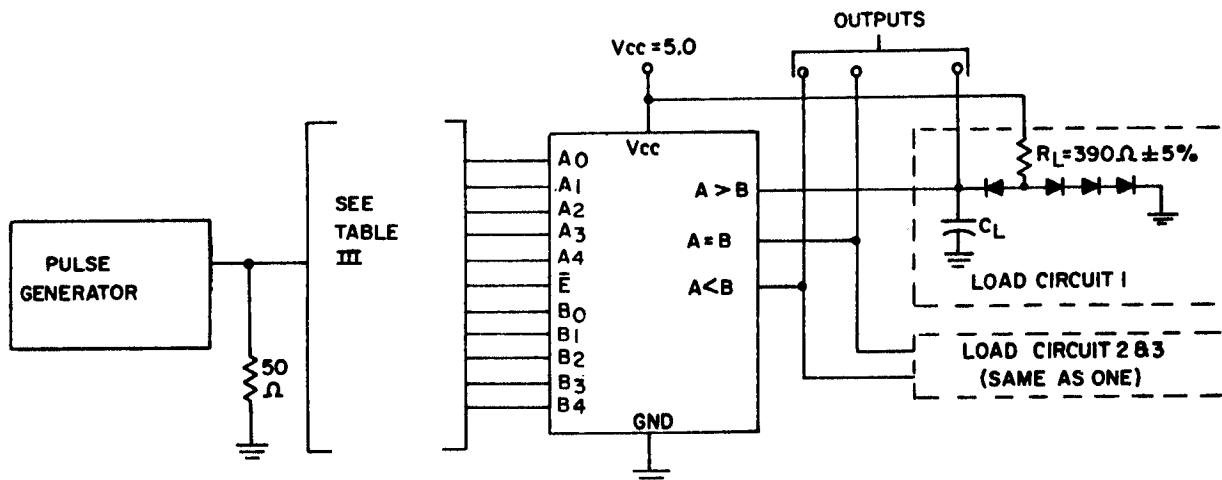
1. CP = 1 MHz, 50% duty cycle, 0-3 V.
2. RL = 300Ω.
3. R₁ = 4 kΩ.
4. R₂ = 10Ω.
5. V_{CC} shall be high enough to ensure 5.0 V minimum at the device terminal.

Figure 4. Burn-in and life test circuit - Continued.

Device type 01**NOTES:**

1. The pulse generator has the following characteristics: $V_{gen} = 3$ V, $t_{THL} = t_{TLH} \leq 10$ ns, $t_p = 500$ ns, PRR = 1 MHz, and $Z_{out} \approx 50\Omega$.
2. $C_L = 50$ pF and includes probe and jig capacitance.
3. All diodes are 1N3064, or equivalent.

FIGURE 5. Switching time test circuit and waveforms for device type 01.

Device type 02

NOTES:

1. The pulse generator has the following characteristics: $V_{gen} = 3 V$, $t_{THL} = t_{TLH} \leq 10 \text{ ns}$, $t_p = 500 \text{ ns}$, PRR = 1 MHz, and $Z_{out} \approx 50\Omega$.
2. $C_L = 50 \text{ pF}$ and includes probe and jig capacitance.
3. All diodes are 1N3064, or equivalent.

FIGURE 6. Switching time test circuit and waveforms for device type 02.

TABLE III. Group A Inspection for device type 01. 1/

Subgroup	Symbol	MIL-STD-883 Test method	Cases	Test no.				Measured terminal				Test limits		Unit								
				B3	A < B IN	A = B IN	A > B IN	A > B OUT	A < B OUT	GND	B0	A0	B1	A1	B2	A2	B3	VCC	Min	Max		
1 $T_C = +25^\circ C$	V_{DH}	3006	1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	-400 μA -400 μA GND	-400 μA -400 μA 16 mA	-400 μA -400 μA 16 mA	GND 2.0 V 0.8 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	0.8 V 0.8 V 2.0 V	14.5 V 12.0 V 0.8 V	A > B OUT A = B OUT A < B OUT	2.4 V 0.4 V -	V	-
	V_{OL}	3007	4 5 6 7 8 9 10 11 12 13 14 15 16 17	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 2.0 V	0.8 V 12.0 V GND	16 mA	16 mA	16 mA	-	2.0 V 2.0 V 0.8 V	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 10.8 V	2.0 V 2.0 V 10.8 V	A > B OUT A = B OUT A < B OUT	0.4 V -	V	-
	V_{IC}		7 8 9 10 11 12 13 14 15 16 17	-12 mA	-12 mA	-12 mA	-	-	-	-	-	-	-	-	-	-	-	B3 A < B IN A = B IN A > B IN B0 B1 A1 A2 B2 B3 A3	-1.5 V -	V	-	
			18 19 20 21 22 23 24 25 26	GND 2.4 V GND -	GND -	GND -	-	-	-	-	-	-	-	-	-	-	-	1.20 uA -	A	-		
	I_{IH1}	3010	18 19 20 21 22 23 24 25 26	1.8 1.9 2.0 2.1 2.2 2.3 2.4 2.5 2.6	2.4 V 2.4 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	2.4 V 5.5 V GND -	A > B IN A = B IN A < B IN B0 B1 A1 A2 B2 B3 A3	1.20 -	A	-		
	I_{IH2}		27 28 29 30 31 32 33 34 35 36 37	GND -	5.5 V 5.5 V GND -	5.5 V 5.5 V GND -	-	-	-	-	-	-	-	-	-	-	-	1.20 10.0 30.0	A	-		
	I_{IH3}		38 39	GND GND	12.4 V 12.4 V	-	-	-	-	-	GND GND	5.5 V 5.5 V	GND GND	5.5 V 5.5 V	GND GND	5.5 V 5.5 V	GND GND	5.5 V 5.5 V	1.20 40	A	-	
	I_{IL1}	3009	40 41 42 43 44 45 46 47 48	0.4 V 15.5 V 10.4 V	-	-	-	-	-	-	5.5 V 10.4 V 5.5 V -	5.5 V 0.4 V 5.5 V -	B3 B0 B1 A1 A2 B2 A3	-2.0 -	A	-						
	I_{IL2}		49 50	0.4 V 0.4 V	-	-	-	-	-	-	-	-	-	-	-	-	-	1.20 40	A	-		

See footnotes at end of table.

TABLE III. Group A inspection for device type 01 - Continued. 1/

Subgroup	Symbol	MIL-STD-883 Cases	Test no.	Test				Test				Test				Test				Test			
				1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	Measured terminal	Test limits	Unit	
TC = +25°C	10S	3011	51	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	A > B OUT	-20	mA	
		*	52	GND	GND	12.0 V	GND	GND	GND	GND	GND	A > B OUT	-20	mA									
		*	53	GND	12.0 V	GND	GND	GND	GND	A < B OUT	-20	mA											
I _{CC}	3005	54	14.5 V	14.5 V	GND	14.5 V	GND	14.5 V	GND	14.5 V	GND	14.5 V	GND	14.5 V	GND	14.5 V	14.5 V	14.5 V	14.5 V	V _{CC}	88	-	

same tests. terminal conditions and limits as subarou 1- except $T_c = +125^{\circ}\text{C}$ and Vir tests are omitted.

3		Same tests, terminal conditions and limits as subgroup 1, except $T_C = -55^\circ\text{C}$ and VIC tests are omitted.																
$T_C = +25^\circ\text{C}$		Truth table tests	55	10.8 V	12.0 V	10.8 V	10.8 V	12.0 V	12.0 V	10.8 V	12.0 V	12.0 V	10.8 V	12.0 V	12.0 V	10.8 V	12.0 V	
56	12.0 V	10.8 V	-	12.0 V	-	10.8 V	-	12.0 V	-	10.8 V	-	12.0 V	-	10.8 V	-	12.0 V	-	
57	2.0 V	-	-	-	-	10.8 V	-	-	-	12.0 V	-	-	-	10.8 V	-	-	-	
58	-	10.8 V	-	-	-	2.0 V	-	-	-	-	10.8 V	-	-	12.0 V	-	-	-	
59	-	2.0 V	-	-	-	-	10.8 V	-	-	-	-	12.0 V	-	-	10.8 V	-	-	
60	-	10.8 V	-	-	-	-	2.0 V	-	-	-	-	-	10.8 V	-	-	12.0 V	-	
61	-	2.0 V	-	-	-	-	-	10.8 V	-	-	-	-	-	12.0 V	-	-	10.8 V	-
62	-	10.8 V	-	-	-	-	-	2.0 V	-	-	-	-	-	-	10.8 V	-	-	
63	-	-	-	-	-	-	-	-	12.0 V	-	-	-	-	-	-	12.0 V	-	
64	-	-	-	-	-	-	-	-	-	12.0 V	-	-	-	-	-	-	12.0 V	-
65	-	-	-	-	-	-	-	-	-	12.0 V	-	-	-	-	-	-	12.0 V	-
66	-	-	-	-	-	-	-	-	-	10.8 V	-	-	-	-	-	-	10.8 V	-
67	-	-	-	-	-	-	-	-	-	10.8 V	-	-	-	-	-	-	10.8 V	-
68	-	-	-	-	-	-	-	-	-	12.0 V	-	-	-	-	-	-	12.0 V	-
69	-	-	-	-	-	-	-	-	-	-	12.0 V	-	-	-	-	-	10.8 V	-
70	-	-	-	-	-	-	-	-	-	-	-	12.0 V	-	-	-	-	10.8 V	-

Acetone solution 1.0% T = 112°C and Tc = 65°C

See footnotes at end of table.

TABLE III. Group A inspection for device type 01 - Continued. 1/

Subgroup	Symbol	MIL-STD-883 Cases Test Method no.	T _C = -5°C	Test Times												Measured terminal	Unit		
				1	2	3	4	5	6	7	8	9	10	11	12	13	14		
	tPHL1	3003 (F19)	88	IN	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	15.0 V	B3 to A < B B0 to A < B A1 to A > B B1 to A < B A2 to A > B B2 to A < B A3 to A > B	
		90	-	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	2.34 ns	
		91	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-	
		92	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-	
		93	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-	
		94	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-	
		95	2.4 V	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-	
	tPHL2	-	96	IN	2.4 V	-	OUT	-	OUT	-	IN	-	-	-	-	-	GND	B3 to A = B B0 to A = B B1 to A = B A2 to A = B	
		-	97	GND	-	-	-	-	-	GND	-	-	-	-	-	-	-	-	
		-	98	-	-	-	-	-	-	GND	-	-	-	-	-	-	-	-	
		-	99	-	-	-	-	-	-	GND	-	-	-	-	-	-	-	-	
	tPHL3	-	100	*	IN	GND	OUT	OUT	OUT	OUT	IN	-	-	-	-	-	A < B to A > B A = B to A > B A > B to A < B		
		-	101	*	GND	IN	OUT	OUT	OUT	OUT	IN	-	-	-	-	-	-	20 ns	
	tPHL5	-	102	*	IN	GND	OUT	OUT	OUT	OUT	IN	-	-	-	-	-	-	-	
		-	103	*	GND	IN	OUT	OUT	OUT	OUT	IN	-	-	-	-	-	-	-	
	tPHL4	-	104	*	IN	IN	OUT	OUT	OUT	OUT	IN	-	-	-	-	-	A = B to A = B	-	
		-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
	tPLH1	-	1105	IN	GND	GND	OUT	OUT	OUT	OUT	GND	GND	GND	GND	GND	2.4 V	-	B3 to A < B B0 to A < B A0 to A > B B1 to A < B A1 to A > B B2 to A > B B3 to A > B	
		-	1106	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	38 ns
		-	1107	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-
		-	1108	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-
		-	1109	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-
		-	1110	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-
		-	1111	-	GND	-	GND	-	GND	-	2.4 V	IN	2.4 V	-	-	-	-	-	-
		-	1112	2.4 V	GND	GND	OUT	OUT	OUT	OUT	GND	GND	GND	GND	GND	IN	-	-	
	tPLH2	-	1113	IN	2.4 V	-	OUT	OUT	OUT	OUT	GND	GND	GND	GND	GND	2.4 V	-	B3 to A = B B0 to A = B A1 to A > B B1 to A < B A2 to A = B B2 to A < B B3 to A > B	
		-	1114	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	49 ns	
		-	1115	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		-	1116	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
	tPLH3	-	1117	*	IN	GND	OUT	OUT	OUT	OUT	GND	IN	-	-	-	-	-	A < B to A > B A = B to A < B A > B to A < B	
		-	1118	*	GND	IN	OUT	OUT	OUT	OUT	-	-	-	-	-	-	-	19 ns	
		-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
	tPLH5	-	1119	*	IN	GND	OUT	OUT	OUT	OUT	GND	IN	-	-	-	-	-	A = B to A > B A1 to A > B B1 to A < B A1 to A > B B2 to A < B A3 to A > B	
		-	1120	*	GND	IN	OUT	OUT	OUT	OUT	-	-	-	-	-	-	-	-	
	tPLH4	-	1121	*	IN	IN	OUT	OUT	OUT	OUT	-	-	-	-	-	-	A = B to A = B	30 ns	
		-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
	tPLH1	-	1122	IN	GND	GND	OUT	OUT	OUT	OUT	IN	2.4 V	-	-	-	2.4 V	GND	B3 to A < B B0 to A < B A1 to A > B B1 to A < B A1 to A > B B2 to A < B A3 to A > B	
		-	1123	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	43 ns	
		-	1124	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		-	1125	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		-	1126	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		-	1127	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	
		-	1128	2.4 V	GND	GND	OUT	OUT	OUT	OUT	GND	IN	2.4 V	-	-	-	-	-	-
		-	1129	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	

See footnotes at end of table.

TABLE III. Group A instructions for device type 01 - Continued. 1/

Subgroup	Symbol	MIL-STD-883 E/F Test method	Cases no.	Test limits												Measured terminal	Unit
				1	2	3	4	5	6	7	8	9	10	11	12	13	
10	tPHL2	(Fig. 5) 131	3003	IN	12.4 V	OUT	-	GND	GND	GND	GND	GND	15.0 V	B3 to A = B	4	43	ns
		"	1312	GND	-	-	-	IN	-	-	-	-	-	B0 to A = B	-	-	-
		"	1313	-	-	-	-	GND	-	-	-	-	-	B1 to A = B	-	-	-
	tPHL3	"	134	-	IN	GND	OUT	-	GND	GND	GND	GND	-	IA < B to A > B	-	26	-
		"	135	-	GND	IN	OUT	-	-	-	-	-	-	IA = B to A > B	-	-	-
	tPHL5	"	136	-	IN	GND	OUT	-	-	-	-	-	-	IA = B to A < B	-	-	-
		"	137	-	GND	IN	OUT	-	-	-	-	-	-	IA > B to A < B	-	-	-
	tPHL4	"	138	-	IN	-	OUT	-	-	-	-	-	-	IA = B to A = B	-	-	-

Same tests, terminal conditions and limits as subgroup 10, except $T_C = -55^\circ C$.

NOTE 5.

- 1/ Pins not designated may be "high" level logic, "low" level logic or open.
 - 2/ Tests shall be performed in sequence.
 - 3/ Output voltages shall be either: (a) $H = 2.4$ V, minimum and $L = 0.4$ V, maximum when using a high speed checker double comparator; or (b) $H > 1.5$ V when using a high speed checker single comparator.

TABLE III. Group A Inspection for device type 02. 1/

Symbol	MIL-STD-883 Test Method	Cases	Test Results												Unit		
			1	2	3	4	5	6	7	8	9	10	11	12	Measured terminal		
$T_C = +25^\circ C$			E	IA < B	B0	B1	B2	B3	B4	GND	A4	A3	A2	A1	A0	VCC	
V_{OL}	3007	1	GND	16 mA	0.8 V	0.8 V	10.8 V	10.8 V	GND	0.8 V	14.5 V	A < B					
	3	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	A > B
	4	2.0 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	A > B
	5	GND	-	-	-	-	-	-	-	-	-	-	-	-	-	-	A > B
	6	2.0 V	16 mA	-	-	-	-	-	-	-	-	-	-	-	-	-	A > B
	7	2.0 V	-	-	-	-	-	-	-	-	-	-	-	-	-	-	A < B
V_{OH}	3006	8	0.8 V	-800 uA	0.8 V	2.0 V	-	-	-	-	-	-	-	-	-	2.4	V
	9	-	-	-	0.8 V	2.0 V	-	-	-	-	-	-	-	-	-	-	-
	10	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	11	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	12	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	13	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	14	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	15	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	16	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	17	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
	18	-	-	-	0.8 V	12.0 V	-	-	-	-	-	-	-	-	-	-	-
V_{ILL}	3009	19	0.4 V	10.4 V	-	-	-	-	-	GND	GND	GND	GND	GND	15.5 V	E	
	20	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-1.4	-3.2	mA
	21	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	22	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	23	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	24	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	25	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	26	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	27	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	28	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
	29	-	-	-	10.4 V	0.4 V	-	-	-	-	-	-	-	-	-	-	-
V_{IC}	30	-12 mA	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	14.5 V	E	
	31	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-1.5	V
	32	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	33	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	34	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	35	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	36	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	37	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	38	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	39	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
	40	-	-	-	-12 mA	-	-12 mA	-	-12 mA	-	-	-	-	-	-	-	-
I_{OS}	3011	41	GND	14.5 V	14.5 V	14.5 V	-	-	-	4.5 V	5.5 V	A < B					
	42	-	-	-	14.5 V	-	-	-	-	-	-	-	-	-	-	-	A > B
	43	-	-	-	GND	-	-	-	-	-	-	-	-	-	-	-	A > B
I_{CC}	3012	44	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
I_{IH1}	3010	45	-	-	2.4 V	-	-	-	-	-	-	-	-	-	-	-	-
	46	-	-	-	2.4 V	-	-	-	-	-	-	-	-	-	-	-	-
	47	-	-	-	2.4 V	-	-	-	-	-	-	-	-	-	-	-	-
	48	-	-	-	2.4 V	-	-	-	-	-	-	-	-	-	-	-	-
	49	-	-	-	2.4 V	-	-	-	-	-	-	-	-	-	-	-	-
	50	-	-	-	2.4 V	-	-	-	-	-	-	-	-	-	-	-	-

See footnotes at end of table.

TABLE III. Group A Inspection for device type 02 - Continued. 1/

Subgroup	Symbol	MIL-STD-883 Cases	Test no.	E	TC = +25°C				TC = -55°C				TC = +125°C				TC = -55°C				Measured terminal				Test limits		Unit																	
					1A < B	B ₀	B ₁	B ₂	B ₃	B ₄	GND	A ₄	A ₃	A ₂	A ₁	A ₀	I _A = B	V _{CC}	I _A = B	V _{CC}	A ₃	A ₂	A ₁	A ₀	B ₀	B ₁	B ₂	B ₃	B ₄	B ₅	B ₆	B ₇	B ₈	B ₉	B ₁₀	B ₁₁	B ₁₂	B ₁₃	B ₁₄	B ₁₅	B ₁₆			
1	T _{1H1}	3010	51	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	15.5 V	15.5 V	15.5 V	15.5 V	A ₃	A ₂	A ₁	A ₀	0	80	mA																		
	T _{1H2}	-	56	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	15.5 V	15.5 V	15.5 V	15.5 V	B ₀	B ₁	B ₂	B ₃	-	200																			
		-	57	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₁	B ₂	B ₃	B ₄	-	-																			
		-	58	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₂	B ₃	B ₄	B ₅	-	-																			
		-	59	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₃	B ₄	B ₅	B ₆	-	-																			
		-	60	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₄	B ₅	B ₆	B ₇	-	-																			
		-	61	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₅	B ₆	B ₇	B ₈	-	-																			
		-	62	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₆	B ₇	B ₈	B ₉	-	-																			
		-	63	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₇	B ₈	B ₉	B ₁₀	-	-																			
		-	64	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₈	B ₉	B ₁₀	B ₁₁	-	-																			
		-	65	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₉	B ₁₀	B ₁₁	B ₁₂	-	-																			
		-	66	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	5.5 V	GND	-	-	-	-	-	-	-	-	-	B ₁₀	B ₁₁	B ₁₂	B ₁₃	-	-																			
2																																												
3																																												
7																																												
				</td																																								

TABLE III. Group A inspection for device type 02 - Continued. 1/

Subgroup	Symbol	MIL-STD-883 Cases	Test												Measure 1 Terminal	Test Times	Unit			
			IE	EF	1	2	3	4	5	6	7	8	9	10	11	12	13	14		
T _C = +25°C	tPHL1	3003 (Fig. 6)	98	IN	2.4 V	2.4 V	2.4 V	2.4 V	GND	A ₄	A ₃	A ₂	A ₁	A ₀	A = B	A > B	V _{CC}			
	tPHL1	99	*	*	*	*	*	*	*	*	2.4 V	2.4 V	2.4 V	2.4 V	OUT	15.0 V	E to A = B	3	16	ns
	tPHL2	100	*	OUT	*	*	*	*	*	*	GND	GND	GND	GND	*	E to A < B	*	14	*	
	tPHL2	101	*	OUT	*	*	*	*	*	*	GND	GND	GND	GND	*	E to A < B	*	17	*	
	tPHL3	102	*	GND	GND	GND	GND	GND	*	2.4 V	2.4 V	2.4 V	2.4 V	OUT	*	E to A > B	*	19	*	
	tPHL3	103	*	GND	GND	GND	GND	GND	*	*	*	*	*	2.4 V	OUT	*	E to A > B	*	17	*
	tPHL4	104	GND	2.4 V	2.4 V	2.4 V	2.4 V	*	*	*	*	*	*	IN	OUT	*	I ₀ to A = B	9	42	*
	tPHL4	105	*	*	*	*	*	*	*	*	*	*	*	IN	2.4 V	*	I ₁ to A = B	*	*	*
	tPHL4	106	*	*	*	*	*	*	*	*	*	*	*	IN	2.4 V	*	I ₂ to A = B	*	*	*
	tPHL4	107	*	*	*	*	*	*	*	*	*	*	*	IN	2.4 V	*	I ₃ to A = B	*	*	*
	tPHL4	108	*	*	*	*	*	*	*	*	*	*	*	IN	2.4 V	*	I ₄ to A = B	*	*	*
	tPHL4	109	*	*	*	*	*	*	*	*	*	*	*	*	*	*	I ₀ to A = B	*	*	*
	tPHL4	110	*	*	*	*	*	*	*	*	*	*	*	*	*	*	I ₁ to A = B	*	*	*
	tPHL4	111	*	*	*	*	*	*	*	*	*	*	*	*	*	*	I ₂ to A = B	*	*	*
	tPHL4	112	*	*	*	*	*	*	*	*	*	*	*	*	*	*	I ₃ to A = B	*	*	*
	tPHL4	113	*	*	*	*	*	*	*	*	*	*	*	*	*	*	I ₄ to A = B	*	*	*
	tPHL5	114	IN	2.4 V	IN	*	*	*	*	*	2.4 V	*	*	*	*	*	I ₀ to A = B	*	*	*
	tPHL5	115	*	2.4 V	*	*	*	*	*	*	*	*	*	*	*	*	I ₁ to A = B	*	*	*
	tPHL5	116	*	2.4 V	IN	*	*	*	*	*	*	*	*	*	*	*	I ₂ to A = B	*	*	*
	tPHL5	117	*	2.4 V	*	*	*	*	*	*	*	*	*	*	*	*	I ₃ to A = B	*	*	*
	tPHL5	118	*	2.4 V	IN	*	*	*	*	*	*	*	*	*	*	*	I ₄ to A = B	*	*	*
	tPHL5	119	IN	2.4 V	IN	*	*	*	*	*	2.4 V	*	*	*	*	*	I ₀ to A = B	*	*	*
	tPHL5	120	*	2.4 V	*	*	*	*	*	*	*	*	*	*	*	*	I ₁ to A = B	*	*	*
	tPHL5	121	*	2.4 V	IN	*	*	*	*	*	*	*	*	*	*	*	I ₂ to A = B	*	*	*
	tPHL5	122	*	2.4 V	*	*	*	*	*	*	*	*	*	*	*	*	I ₃ to A = B	*	*	*
	tPHL5	123	*	*	*	*	*	*	*	*	2.4 V	IN	*	*	*	*	I ₄ to A = B	*	*	*
	tPHL6	124	*	OUT	*	*	*	*	*	2.4 V	*	*	*	*	IN	*	I ₀ to A < B	6	27	*
	tPHL6	125	*	*	*	*	*	*	*	2.4 V	*	*	*	*	IN	*	I ₀ to A < B	6	25	*
	tPHL7	126	*	*	IN	GND	GND	GND	*	GND	GND	GND	GND	*	GND	*	I ₀ to A < B	3	22	*
	tPHL7	127	*	*	IN	*	*	*	*	*	*	*	*	*	*	*	I ₀ to A < B	*	20	*
	tPHL8	128	*	*	GND	*	*	*	*	*	*	*	*	*	OUT	*	I ₀ to A > B	*	22	*
	tPHL8	129	*	*	GND	*	*	*	*	*	*	*	*	*	IN	*	I ₀ to A > B	*	20	*
	tPHL9	130	*	*	IN	2.4 V	2.4 V	2.4 V	*	2.4 V	2.4 V	2.4 V	2.4 V	OUT	*	I ₀ to A > B	6	27	*	
	tPHL9	131	*	*	IN	2.4 V	2.4 V	2.4 V	*	2.4 V	2.4 V	2.4 V	2.4 V	OUT	*	I ₀ to A > B	6	15	*	

nd of table.

See footer

TABLE III. Group A Inspection for device type 02 - Continued. 1/

Subgroup	Symbol	MIL-STD-883 Cases E, F	Test Limits												Measured terminal	Min	Max	
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
10	t _{PLH1}	3003 (Fig. 6) 1132	IN	12.4 V	12.4 V	12.4 V	2.4 V	GND	12.4 V	12.4 V	12.4 V	2.4 V	OUT	15.0 V	E to A > B	3	22	
T _C = +125°C	t _{PHL1}	-	1133	-	-	-	-	-	-	2.4 V	12.4 V	12.4 V	2.4 V	OUT	-	E to A > B	-	19
	t _{PLH2}	-	1134	-	OUT	-	-	-	-	GND	GND	GND	GND	-	E to A < B	-	25	
	t _{PHL2}	-	1135	-	OUT	-	-	-	-	GND	GND	GND	GND	-	E to A < B	-	21	
	t _{PLH3}	-	1136	-	GND	GND	GND	GND	-	2.4 V	12.4 V	12.4 V	2.4 V	OUT	-	E to A > B	-	25
	t _{PHL3}	-	1137	-	GND	GND	GND	GND	-	-	-	-	OUT	-	E to A > B	-	21	
	t _{PLH4}	-	1138	GND	12.4 V	12.4 V	12.4 V	-	-	-	IN	12.4 V	OUT	-	I _A to A = B	9	55	
		-	1139	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
		-	1140	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
		-	1141	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
		-	1142	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
	t _{PHL4}	-	1143	-	-	-	-	-	-	2.4 V	-	-	IN	12.4 V	-	-	-	
		-	1144	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
		-	1145	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
		-	1146	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
		-	1147	-	-	-	-	-	-	-	IN	12.4 V	-	-	I _A to A = B	-	-	
	t _{PLH5}	-	1148	IN	2.4 V	-	-	-	-	2.4 V	-	-	-	-	I _B to A = B	-	-	
		-	1149	2.4 V	IN	-	-	-	-	-	-	-	-	-	I _B to A = B	-	-	
		-	1150	-	2.4 V	IN	-	-	-	-	-	-	-	-	I _B to A = B	-	-	
		-	1151	-	-	2.4 V	IN	-	-	-	-	-	-	-	I _B to A = B	-	-	
		-	1152	-	-	-	2.4 V	IN	-	-	-	-	-	-	I _B to A = B	-	-	
	t _{PHL5}	-	1153	IN	-	-	-	-	2.4 V	-	-	-	-	-	I _B to A = B	-	-	
		-	1154	2.4 V	IN	-	-	-	-	-	-	-	-	-	I _B to A = B	-	-	
		-	1155	-	2.4 V	IN	-	-	-	-	-	-	-	-	I _B to A = B	-	-	
		-	1156	-	-	2.4 V	IN	-	-	-	-	-	-	-	I _B to A = B	-	-	
		-	1157	-	-	-	2.4 V	IN	-	-	-	-	-	-	I _B to A = B	-	-	
	t _{PLH6}	-	1158	-	OUT	-	-	-	2.4 V	-	-	-	IN	-	I _A to A < B	6	39	
	t _{PHL6}	-	1159	-	-	-	-	-	-	2.4 V	-	-	-	IN	I _A to A < B	6	32	
	t _{PLH7}	-	1160	-	IN	GND	GND	GND	GND	GND	GND	GND	GND	-	I _B to A < B	3	30	
	t _{PHL7}	-	1161	-	-	IN	GND	GND	GND	GND	GND	GND	GND	-	I _B to A < B	3	26	

See footnotes at end of table.

TABLE III. Group A inspection for device type 02 - continued. 1/

Sub group	Symbol	MIL-STG-803 method	Cases no.	Test								Test								Measured terminal	Test limits Min	Test limits Max
				1 E, F	2 A < B	3 B1	4 B2	5 B3	6 B4	7 GND	8 A4	9 A3	10 A2	11 A1	12 A0	13 IA = B	14 IA > B	15 VCC	16 OUT			
10 $T_C = +125^\circ C$	tPLH8 (Fig. 6)	162	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	GND	A0 to A > B	3	30	
	tPHH8	*	163	*	GND	GND	GND	GND	GND	*	GND	GND	GND	GND	GND	GND	GND	GND	*	A0 to A > B	3	25
	tPLH9	*	164	*	IN	2.4 V	2.4 V	2.4 V	2.4 V	*	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	*	B0 to A > B	6	39
	tPHH9	*	165	*	IN	2.4 V	2.4 V	2.4 V	2.4 V	*	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	2.4 V	*	B0 to A > B	6	35
11	Same conditions and limits as subgroup 10, except $T_C = -55^\circ C$.																					

NOTES:
 1/ Pins not designated may be "high" level logic, "low" level logic or open.
 2/ Tests shall be performed in sequence.
 3/ Output voltages shall be either: (a) $H = 2.4 V$ minimum and $L = 0.4 V$ maximum, when using a high speed checker double comparator; or (b) $H \geq 1.5 V$ when using a high speed checker single comparator.

4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883 and as follows:

- a. Electrical test requirements shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6 of table I of method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883. Electrical test requirements shall be as specified in table II herein.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test (method 1005 of MIL-STD-883) conditions:
 - (1) Test condition D or E, using the circuit shown on figure 4, or equivalent.
 - (2) $T_A = +125^\circ\text{C}$ minimum.
 - (3) Test Duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.4 Group D inspection. Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883. End-point electrical parameters shall be as specified in table II herein.

4.5 Methods of inspection. Methods of inspection shall be specified as follows:

4.5.1 Voltage and current. All voltages given are referenced to the microcircuit ground terminal. Currents given are conventional and positive when flowing into the referenced terminal.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

6.2 Ordering data. The acquisition document should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- c. Requirements for certificate of compliance, if applicable.
- d. Requirements for notification of change of product or process to the contracting activity in addition to notification to the qualifying activity, if applicable.
- e. Requirements for failure analysis (including required test condition of method 5003 of MIL-STD-883), corrective action and reporting of results, if applicable.
- f. Requirements for product assurance options.

g. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements shall not apply to direct purchase by or direct shipment to the Government.

h. Requirements for "JAN" marking.

6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-M-38510, MIL-STD-133I, and as follows:

GND - - - - -	Ground zero voltage potential.
I _{IN} - - - - -	Current flowing into an input terminal.
V _{IN} - - - - -	Voltage level at an input terminal.

6.4 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class B (see 1.2.2), lead material and finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.5 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

Military device type	Generic-industry type
01	5485
02	9324

6.6 Manufacturers' designators. Manufacturers' circuits which form a part of this specification are designated with an "X" as shown in table IV herein.

TABLE IV. Manufacturers' designations.

Device type	Circuit			
	A		B	C
	Fairchild Semiconductor	Motorola	Signetics	National Semiconductor
01	X		X	X
02	X	X		

Custodians:

Army - ER
Navy - EC
Air Force - 17

Review activities:

Army - AR, MI
Navy - OS, SH, TD
Air Force - 11, 19, 85, 99
DLA - ES

User activities:

Army - SM
Navy - AS, CG, MC

Preparing activity:

Air Force - 17

Agent:
DLA - ES

(Project 5962-0878)